

5.0 AMP SURFACE MOUNT SCHOTTKY BARRIER RECTIFIERS

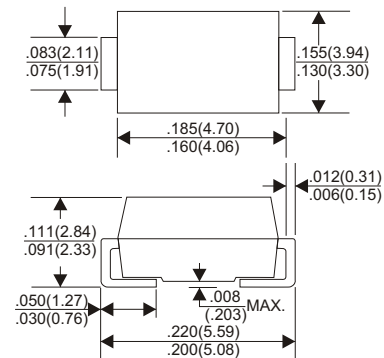
Features:

- * Low forward voltage drop
- * High current capability
- * High reliability
- * High surge current capability
- * Epitaxial construction

Mechanical Data:

- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Lead: Axial leads, solderable per MIL-STD-202, method 208 guaranteed
- * Polarity: Color band denotes cathode end
- * Mounting position: Any
- * Weight: 0.093 grams
- * Both normal and Pb free product are available:
- * Normal: 80~95%Sn, 5~20%Pb
- * Pb free: 99 Sn above can meet Rohs environment substance directive request

DO-214AA(SMB)



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
 Single phase half wave, 60Hz, resistive or inductive load.
 For capacitive load, derate current by 20%.

TYPE NUMBER	SK 52B	SK 54B	SK 56B	SK 58B	SK 510B	SK 515B	SK 520B	UNITS
Marking Code	SK52 SS52	SK54 SS54	SK56 SS56	SK58 SS58	SK510 SS510	SK515 SS515	SK520 SS520	-
Maximum Recurrent Peak Reverse Voltage	20	40	60	80	100	150	200	V
Maximum RMS Voltage	14	28	42	56	70	105	140	V
Maximum DC Blocking Voltage	20	40	60	80	100	150	200	V
Maximum Average Forward Rectified Current See Fig. 1	5.0							A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	150							A
Maximum Instantaneous Forward Voltage at 5.0A	0.55	0.70	0.85				V	
Maximum DC Reverse Current Ta=25°C	0.2							mA
at Rated DC Blocking Voltage Ta=100°C	20							mA
Typical Junction Capacitance (Note1)	380							pF
Typical Thermal Resistance R JA (Note 2)	10							°C/W
Operating Temperature Range Tj	-65 — +150							°C
Storage Temperature Range TSTG	-65 — +150							°C

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.
2. Thermal Resistance Junction to Ambient

RATING AND CHARACTERISTIC CURVES (SK52B THRU SK520B)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

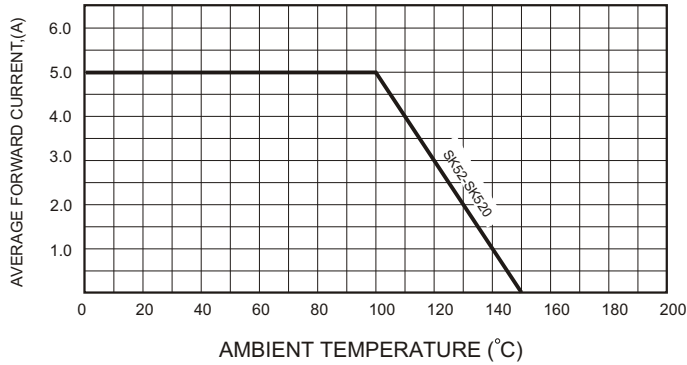


FIG.2-TYPICAL FORWARD CHARACTERISTICS

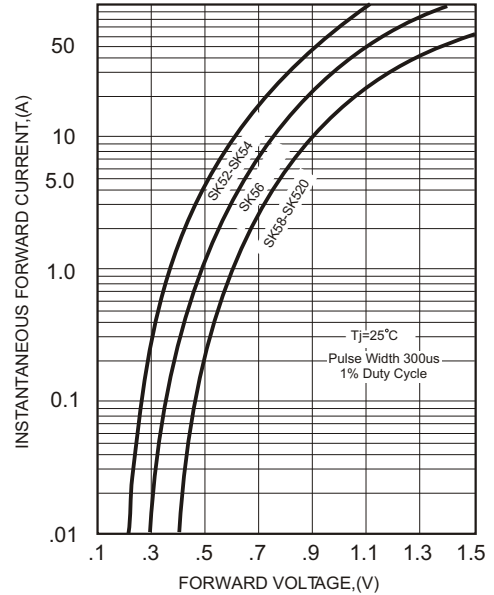


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

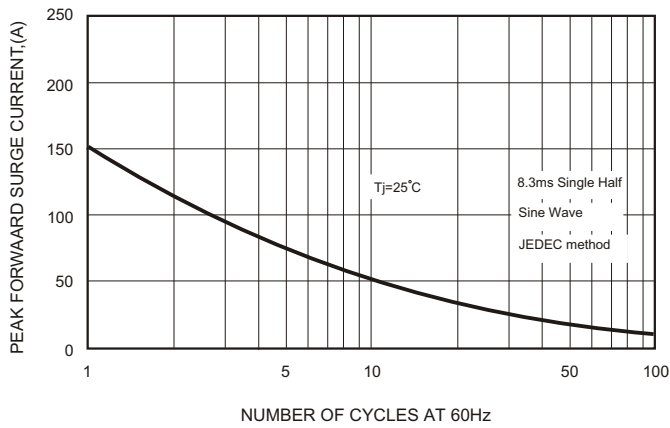


FIG.5 - TYPICAL REVERSE CHARACTERISTICS

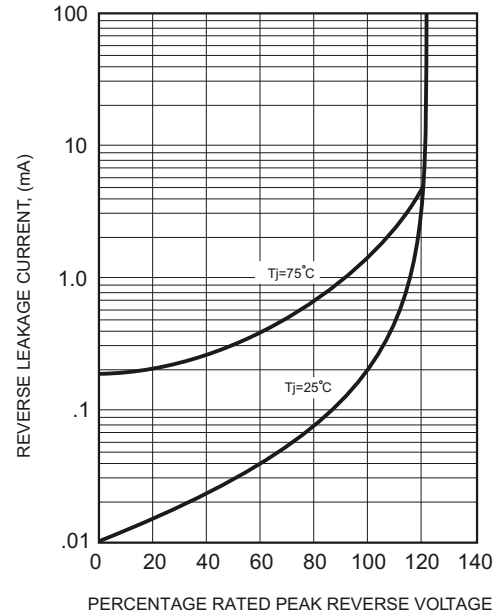
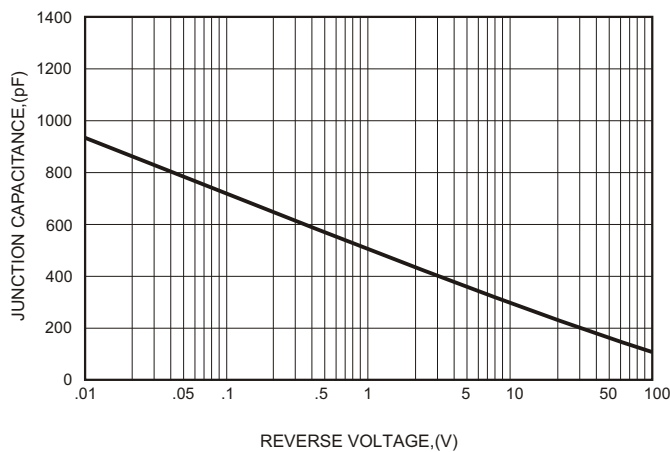
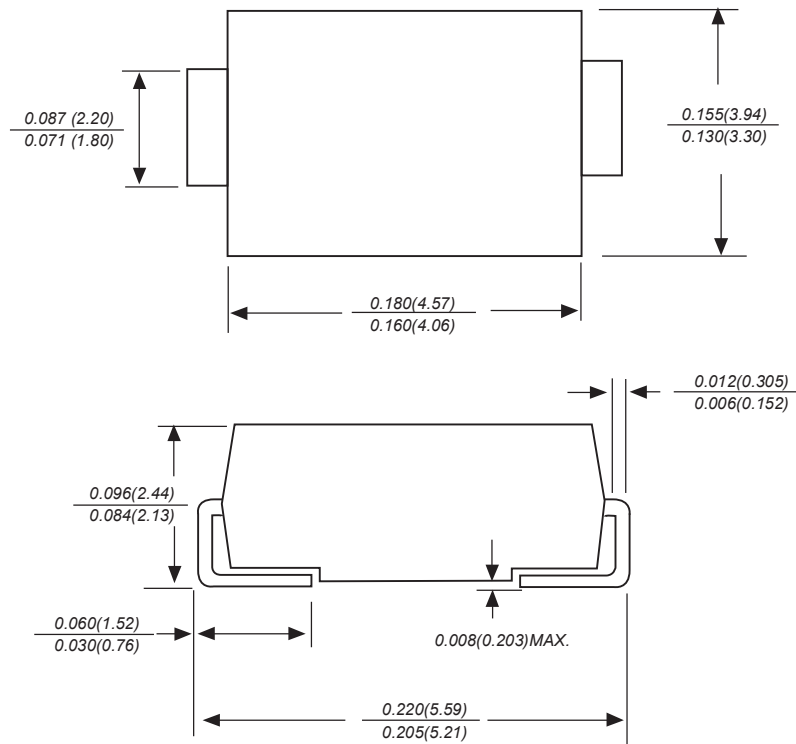


FIG.4-TYPICAL JUNCTION CAPACITANCE

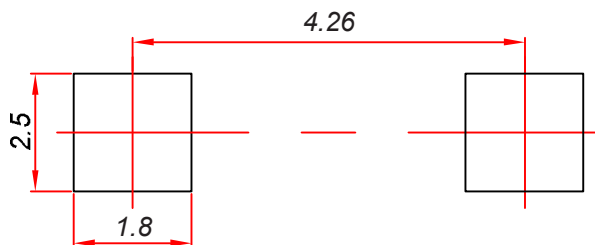


SMB Package Outline Dimensions



Dimensions in inches and (millimeters)

SMB Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.

Reel Taping Specifications For Surface Mount Devices-SMB

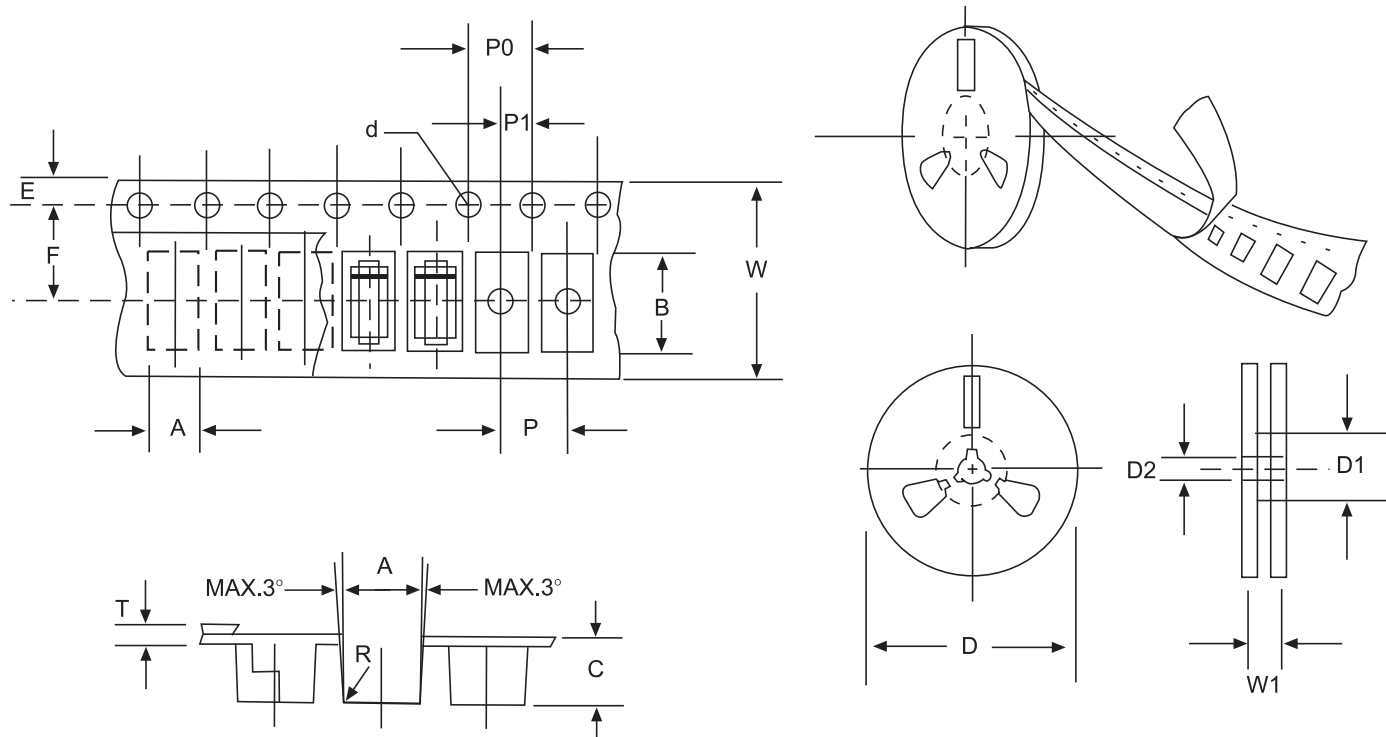


FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	SMBG mm(inch)
Carrier width	A	4.09±0.1(0.161±0.004)
Carrier length	B	5.82±0.1(0.229±0.004)
Carrier depth	C	2.50±0.1(0.100±0.004)
Sprocket hole	d	1.55±0.05 (0.061±0.002)
Reel outside diameter	D	330±2.0(13±0.079)
Reel inner diameter	D1	75 ±1.0 (2.95 ±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Strocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.65±0.05(0.222±0.002)
Punch hole pitch	P	8.0±0.1(0.315±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Total tape thickness	T	0.32±0.1 (0.013±0.004)
Tape width	W	12.0±0.2(0.472±0.008)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.